

PMP8750_RevB_7 BOM

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C701	1	DNP	DNP	SMT Radial G		Panasonic
C702, C703	2	2.2uF	CAP, CERM, 2.2uF, 50V, +/-10%, X7R, 1206	1206	GRM31CR71H225KA88L	MuRata
C704	1	0.01uF	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H103KA01D	MuRata
C705	1	22uF	CAP, CERM, 22uF, 10V, +/-20%, X5R, 1210	1210	C3225X5R1A226M	TDK
C707	1	2200pF	CAP, CERM, 2200pF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E222KA01D	MuRata
C708	1	27pF	CAP, CERM, 27pF, 50V, +/-5%, C0G/NP0, 0603	0603	06035A270JAT2A	AVX
C711	1	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	06035C104KAT2A	AVX
D701	1		Diode, Schottky, xxV, xxA, [PackageReference]	Used in PnP output	B260	Used in BOM report
J701, J702	2		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm	ED555/2DS	On-Shore Technology
L701	1	33uH	Inductor, Shielded Drum Core, Ferrite, 33uH, 2.3A, 0.09 ohm, SMD	MSS1038	MSS1038-333MLB	Coilcraft
R701	1	69.8k	RES, 69.8k ohm, 1%, 0.1W, 0603	0603	CRCW060369K8FKEA	Vishay-Dale
R702	1	11.3k	RES, 11.3k ohm, 1%, 0.1W, 0603	0603	CRCW060311K3FKEA	Vishay-Dale
R703	1	301k	RES, 301k ohm, 1%, 0.1W, 0603	0603	CRCW0603301KFKEA	Vishay-Dale
R704	1	34.8k	RES, 34.8k ohm, 1%, 0.1W, 0603	0603	CRCW060334K8FKEA	Vishay-Dale
R705	1	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	CRCW060349R9FKEA	Vishay-Dale
R706	1	80.6k	RES, 80.6k ohm, 1%, 0.1W, 0603	0603	CRCW060380K6FKEA	Vishay-Dale
R707	1	8.87k	RES, 8.87k ohm, 1%, 0.1W, 0603	0603	CRCW06038K87FKEA	Vishay-Dale
TP701, TP703, TP704, TP705, TP706, TP707, TP708, TP709	8	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone
TP702, TP710	2	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
U701	1	TPS54140-Q1 (alternative part: TPS57140-Q1)	IC, DC-DC Converter With Eco-Mode, 1.5A, 42V	MSOP-10	TPS54140-Q1 (alternative part: TPS57140-Q1)	TI

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